

## **IOT3D | 3D for Internet of Things**

## **Project Sheet (EN)**

Cofinanciado por:







Project nº

15904

## 3D 4 IOT | 3D for Internet of Things

## **Project overview**

The "3D 4 IoT" project will be developed at NANIUM's industrial unit in Mindelo, Vila do Conde and the capacity to be installed will be the basis for NANIUM's product and market diversification strategy. The new products, WLP services for 3D packages, will be targeted primarily to the IoT market.

This project will allow NANIUM to have greater production capacity and thus accommodate the growth in the offer of different WLP solutions successfully developed over the last few years by its R&D team. It should be noted that this investment reflects the incorporation of worldwide innovative technology that was developed by NANIUM within the WLP processes.

Specifically, the "3D 4 IoT" project will allow NANIUM to increase its production capacity not only in physical terms but also in terms of diversifying WLP technologies, namely:

- (a) Ability to produce more advanced wafer geometries below 28nm;
- b) Ability to offer the assembly of multi-chip packages in volume and with high precision and process capability;
- c) Ability to offer the market very thin packages, far ahead of what the competition currently offers;
- d) Ability to install more advanced lithography equipment, which allows to lower the metallization geometries to values below 10µm.

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e) Ability to offer RDL multi-layer and double-sided RDL (metallic redistribution on both sides of the package) packages.	
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